

date 03/31/2017

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MODEL: HSS-B20-053H-01 | DESCRIPTION: HEAT SINK

FEATURES

- TO-220 package
- round hole for component attachment
- solder pins for secure PCB mounting
- black anodized finish





thermal resistance¹ power dissipation¹ @ 75°C ∆T, @ 75°C ∆T, @ 1 W, @ 1 W. @ 1 W, 400 LFM nat conv 200 LFM nat conv nat conv (°C/W) (°C/W) (°C/W) (°C/W) (W) 15.79 20.27 4.22 4.75 HSS-B20-053H-01 5.83

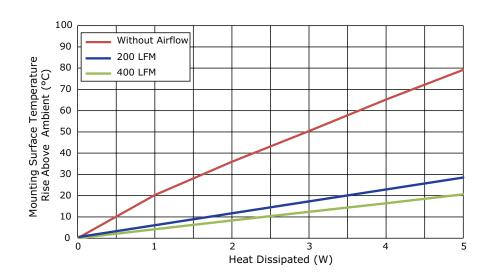
Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient ($\Delta T = Ths - Ta$) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	20.27	5.83	4.22
2	35.97	11.51	8.34
3	50.37	17.06	12.42
4	65.25	22.79	16.41
5	79.19	28.53	20.60

Ths: "hot spot" temperature measured on the heatsink

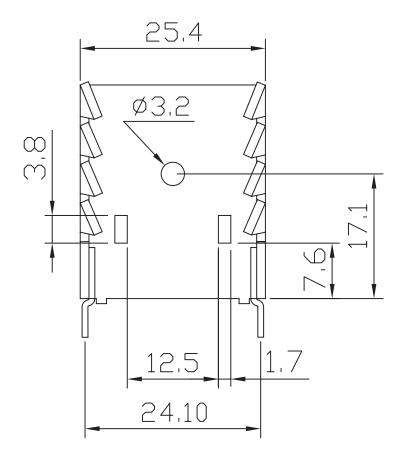
Ta: ambient temperature

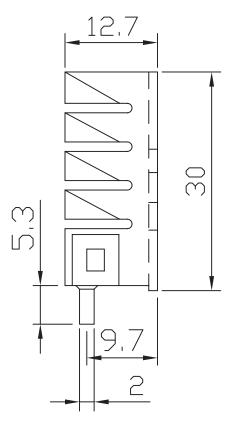


MECHANICAL DRAWING

units: mm tolerance: ±0.5 mm

MATERIAL	AL1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	5.0 g





REVISION HISTORY

rev.	description	date
1.0	initial release	03/31/2017

The revision history provided is for informational purposes only and is believed to be accurate.



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CUI offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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